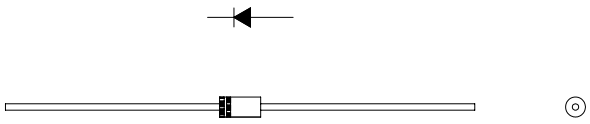
Nihon Inter Electronics Corporation

FRD Type :11DF2

OUTLINE DRAWING



FEATURES

* Miniature Size
* Ultra - Fast Recovery
* Low Forward Voltage drop
* Low Power Loss, High Efficiency
* High Surge Capability
* 200 Volts thru 400 Volts Types Available
* 52mm Inside Tape Spacing Package Available

Maximum Ratings

Approx Net Weight:0.33g

Rating	Symbol	11DF2			Unit
Repetitive Peak Reverse Voltage	V_{RRM}	200			V
Non-repetitive Peak Reverse Voltage	V_{RSM}	220			V
Average Rectified Output Current	I_O	1.0	Ta=27℃ ∗1 Ta=63℃ ∗2	50Hz Half Sine Wave Resistive Load	A
RMS Forward Current	$I_{F(RMS)}$	1.57			A
Surge Forward Current	I_{FSM}	30	50Hz Half Sine Wave,1cycle, Non-repetitive		A
Operating JunctionTemperature Range	Tjw	- 40 to + 150			℃
Storage Temperature Range	Tstg	- 40 to + 150			℃

Electrical • Thermal Characteristics

Characteristics	Symbol	Conditions		Min.	Typ.	Max.	Unit
Peak Reverse Current	I_{RM}	Tj= 25℃, V_{RM}= V_{RRM}		-	-	10	μA
Peak Forward Voltage	V_{FM}	Tj= 25℃, I_{FM}= 1.0A		-	-	0.98	V
Reverse Recovery Time	trr	-di/dt=50A/μs, I_{FM}=1A, Ta=25		-	-	30	ns
Thermal Resistance	Rth(j-a)	Junction to Ambient	∗1 : Without Fin	-	-	115	℃/W
			∗2 : P.C. Board mounted			81	

∗1 : Without Fin or P.C. Board

∗2 : P.C. Board mounted(L=8mm,Print Lands =10x10mm,Both Sides)

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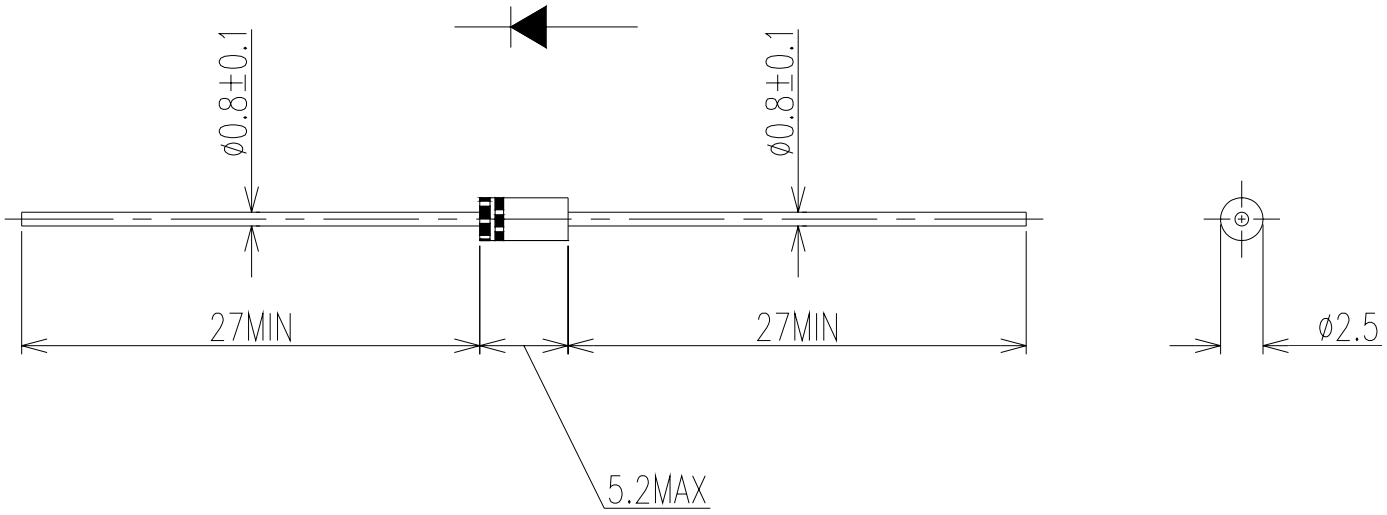
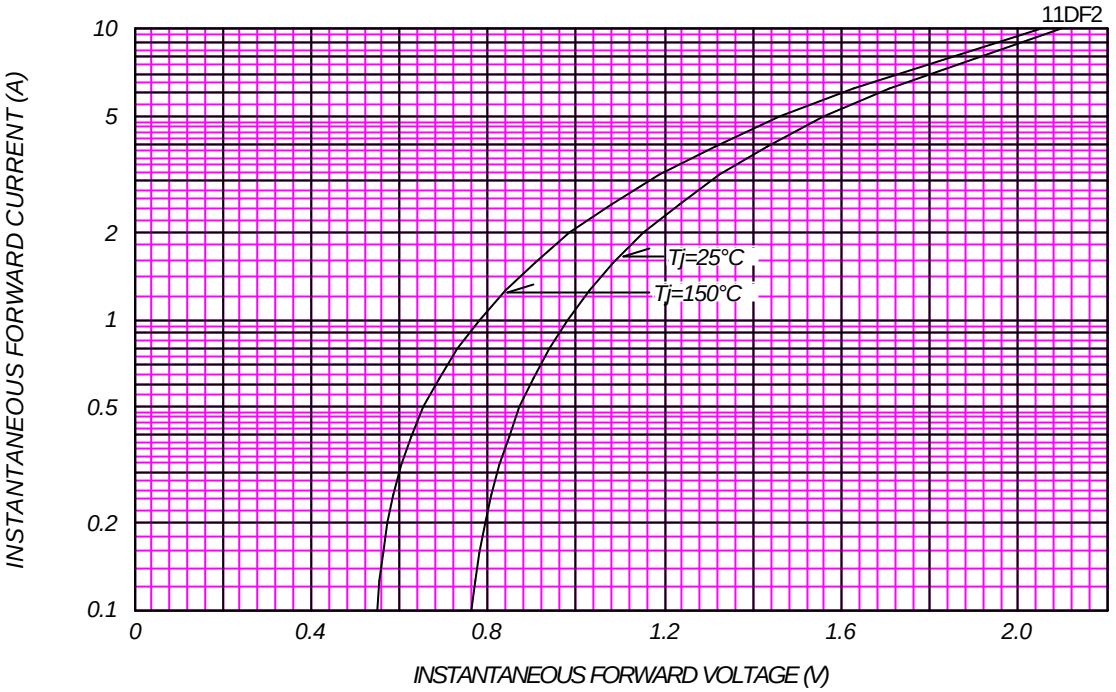
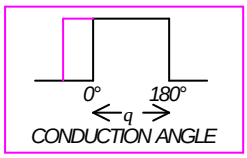
11DF2 OUTLINE DRAWING (Dimensions in mm)

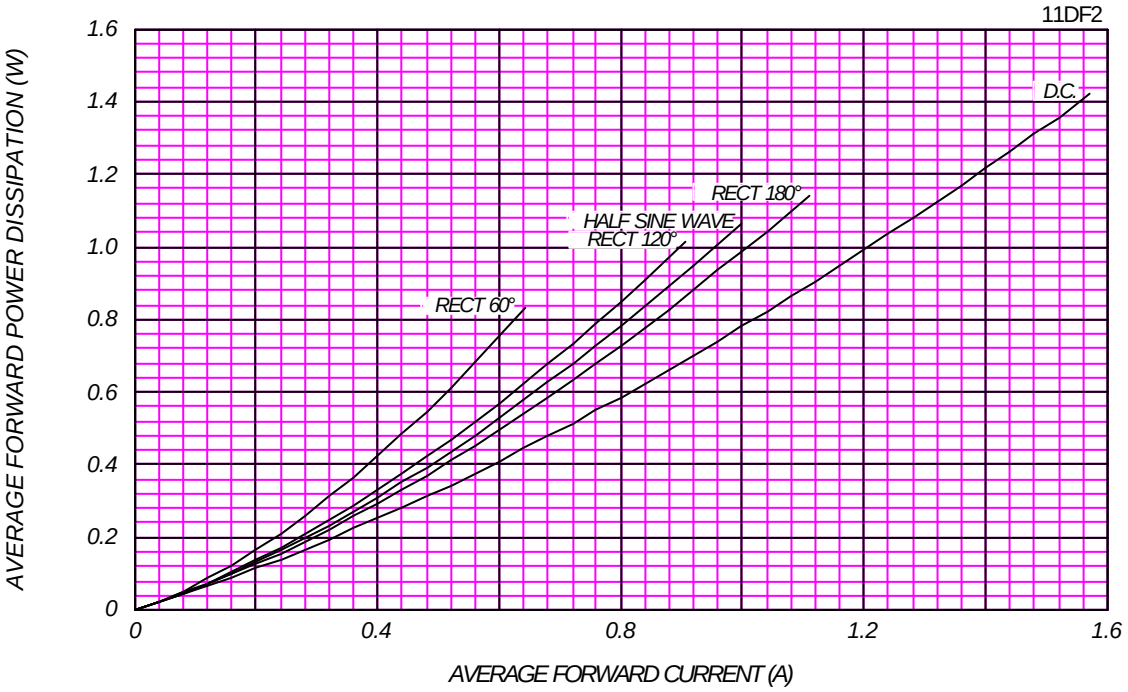


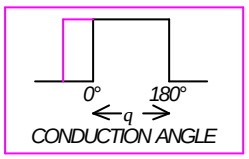
FORWARD CURRENT VS. VOLTAGE





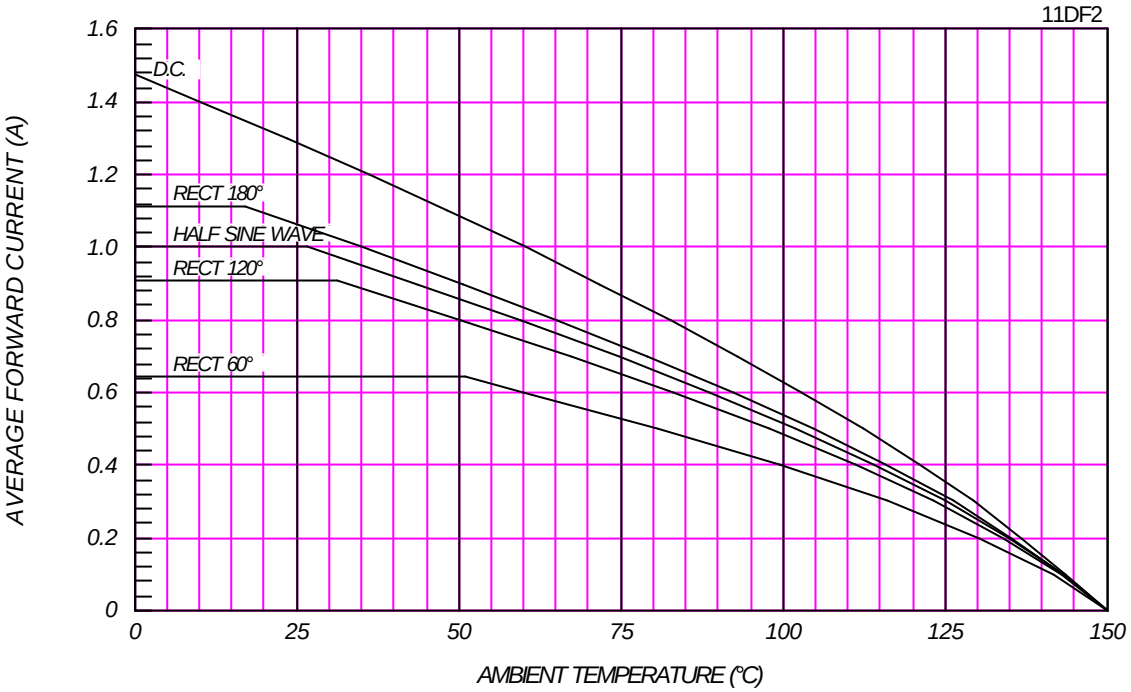
AVERAGE FORWARD POWER DISSIPATION

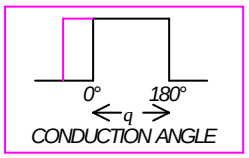




AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATURE

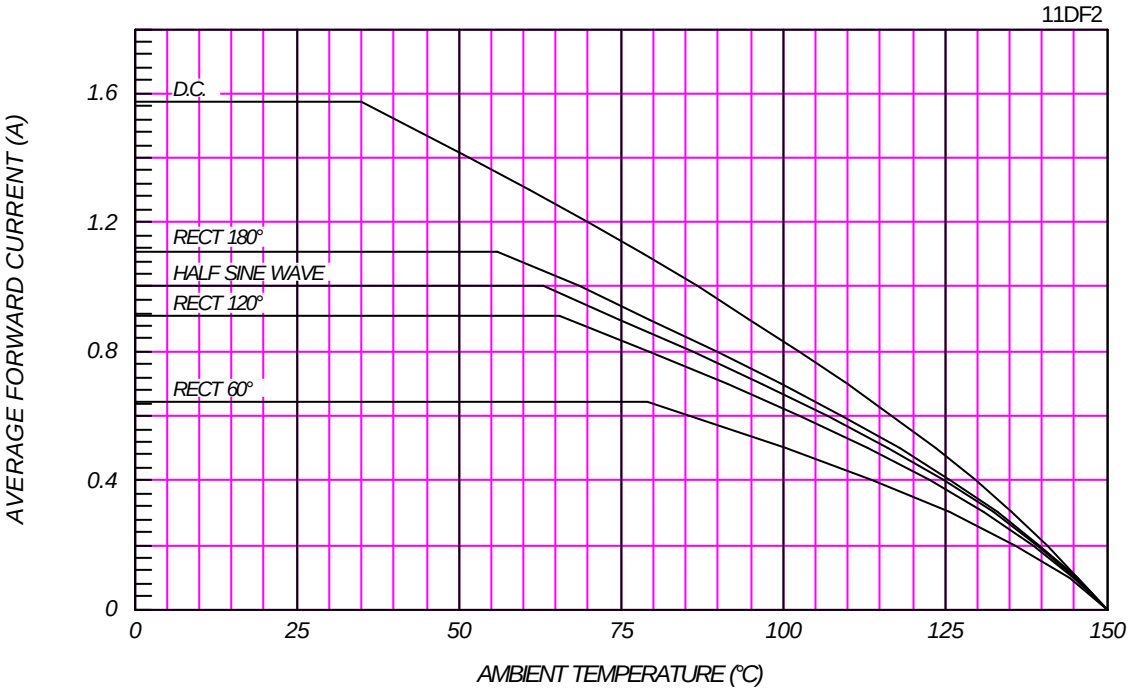
Without Fin or P.C. Board





AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATURE

P.C. Board mounted (L=8mm,Print Land=10×10mm,Both Sides)



SURGE CURRENT RATINGS

f=50Hz,Half Sine Wave,Non-Repetitive,No Load